



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



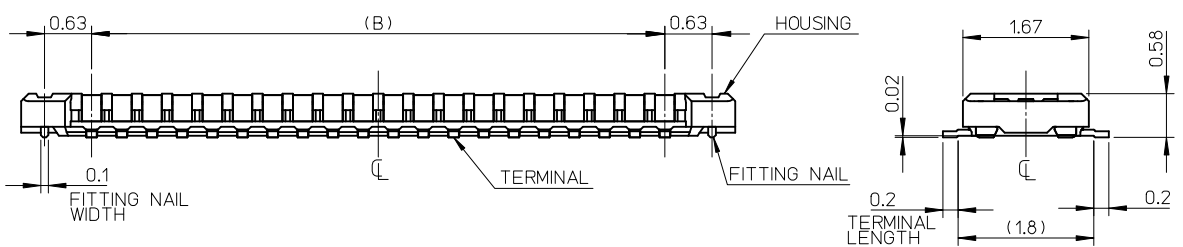
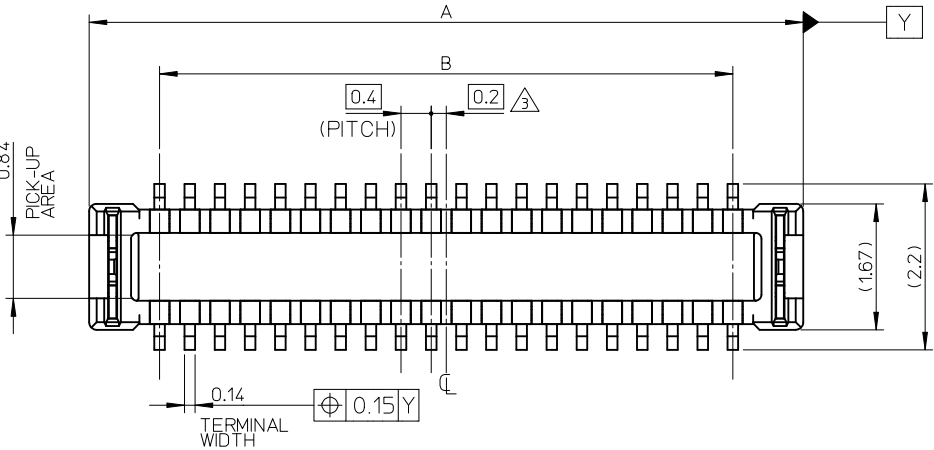
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注記 NOTES

1. 使用材料 MATERIAL
 ハウジング : 液晶ポリマー (LCP) UL94V-0 (黒)
 60極品はLCPのグレードが異なります。
 HOUSING: LIQUID CRYSTAL POLYMER UL94V-0 (COLOR: BLACK)
 ターミナル : 銅合金
 TERMINAL : COPPER ALLOY
 金具 : 銅合金
 FITTING NAIL : COPPER ALLOY

△ (全極数 / 2) = 偶数の場合に適用。
 APPLY FOR (CIRCUIT/2)-EVEN.

2. メッキ仕様 PLATING
 ターミナル TERMINAL

金メッキ
 GOLD
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL

※コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。
 DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.

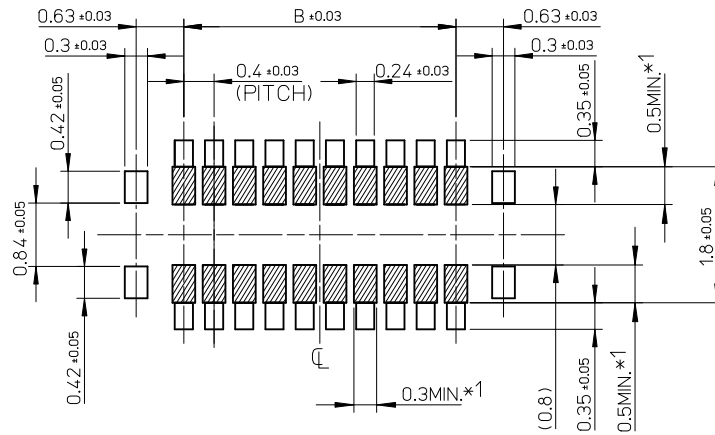
- 金具 FITTING NAIL

錫メッキ
 Tin PLATING
 下地メッキ: ニッケルメッキ
 UNDER PLATING: NICKEL

4. 嵌合相手 : 503304 シリーズ
 MATE WITH : 503304 SERIES.
5. テール平坦度は、0.08 以下
 テール及び金具の平坦度は、0.1 以下
 TAIL COPLANARITY TO BE 0.08 MAXIMUM.
 TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.

11.6	13.47	503308-6020	60
9.6	11.47	503308-5010	50
8.4	10.27	503308-4410	44
8.0	9.87	503308-4210	42
7.6	9.47	503308-4010	40
5.6	7.47	503308-3010	30
4.8	6.67	503308-2610	26
4.4	6.27	503308-2410	24
3.6	5.47	503308-2010	20
3.2	5.07	503308-1810	18
2.8	4.67	503308-1610	16
2.0	3.87	503308-1210	12
B	A	EMBOSSED PACKAGE	
		オーダー番号 ORDER No.	極数 CIRCUITS
		CONNECTOR SERIES No. : 503308-**09	

REVISED EC NO: J2011-0495 DRWN: M. AKAHASHI 03/20/10/05/14 CHKD: 20/10/05 APPR: MSASAO 20/10/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KSASAKI	DATE 2008/04/17	TITLE 0.4 B-TO-B CONN. HGT=0.7 W=2.6 PLUG ASS'Y		
	10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA	DATE 2008/04/17	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2008/04/17	DOCUMENT NO. SD-503308-001		
	ANGULAR ±1 °		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



*1 パターン引き回し、および半田禁止エリア
 (当該箇所においては、これと接する回路以外の配線を禁止する。
 また、接する回路を配線する場合はレジストを施し、この部分に
 半田は無きこととする。)

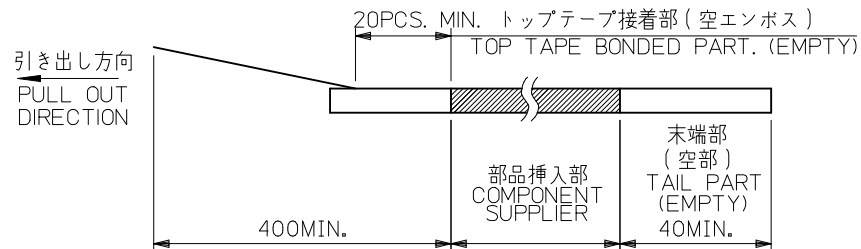
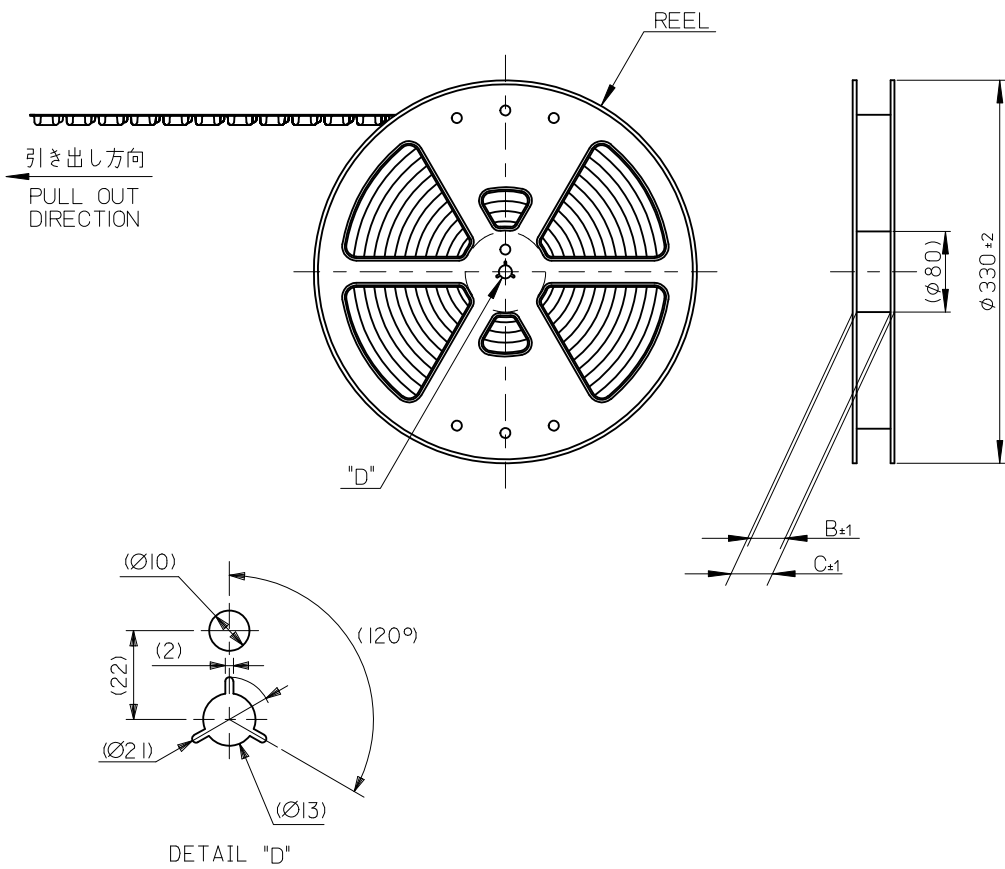
*1 PROHIBITED AREA OF PATTERN WIRING AND SOLDER.
 (FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER
 CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)

RECOMMENDED P.W. BOARD
 PATTERN LAYOUT

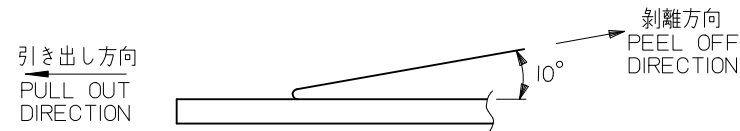
REVISED EC NO: J2011-0495 DRWN: MTAKAHASHI 2010/05/14 CHKD: 2010/10/05 APPR: MSASAO 2010/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY KSASAKI	DATE 2008/04/17	TITLE 0.4 B-TO-B CONN. HGT=0.7 W=2.6 PLUG ASS'Y			
	10 OVER 30 UNDER	± 0.25	CHECKED BY THIRATA	DATE 2008/04/17				
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2008/04/17	MOLEX INCORPORATED			
	ANGULAR ± 1 °		MATERIAL NO. SEE CHART					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

注記 NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 3000 個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

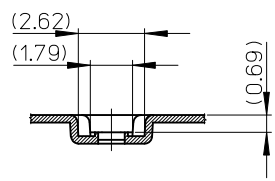
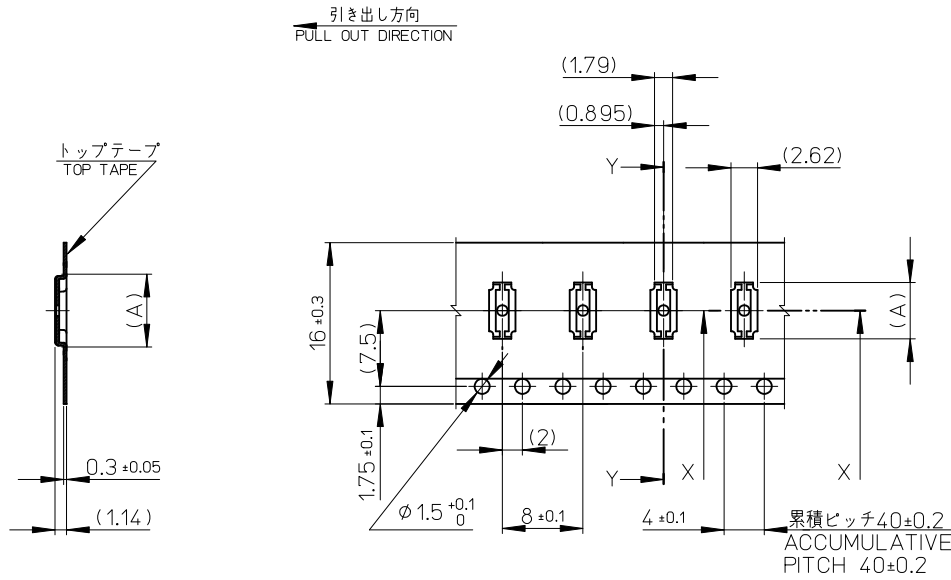


- トップテープの剥離強度: 0.1N~1.3N(10gf~130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N~1.3N(10gf~130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET, OTHER
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2011-0495 DRWN:KSASAKI CHKD: APPR:MSASAO	DESCRIPTION 2010/08/16 2010/10/05 2010/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	MODEL NO.	503308-**10	
		10 UNDER	±0.2	DRAWN BY KSASAKI		DATE 2008/12/12	TITLE	THIRD ANGLE PROJECTION		
		10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA		DATE 2008/12/12	0.4 B-TO-B CONN. HGT=0.7 PLUG ASSY EMBSTP PKG			
		30 OVER	±0.3	APPROVED BY MSASAO		DATE 2008/12/12	MOLEX INCORPORATED			
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503308-002		SHEET NO. 1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



SECTION X-X

SECTION Y-Y

16mm 幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	6.79	503308-2610	26
			6.39	503308-2410	24
			5.59	503308-2010	20
			5.19	503308-1810	18
			4.79	503308-1610	16
			3.99	503308-1210	12
キャリアテープ幅 CARRIER TAPE WIDTH			C	B	(A)
			MATERIAL No.		CKT.
			MODEL No.		503308-**-10

REVISED EC NO: J2011-0495 DRW:KSASAKI CHKD: APPR:MSASAO 2010/08/16 2010/10/05 2010/10/05	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY DATE		TITLE		0.4 B-TO-B CONN. HGT=0.7 PLUG ASSY EMBSTP PKG		
		10 OVER 30 UNDER	±0.25	KSASAKI 2008/12/12		CHECKED BY DATE				
		30 OVER	±0.3	THIRATA 2008/12/12		APPROVED BY DATE		MOLEX INCORPORATED SD-503308-002		
		ANGULAR	±1 °	MSASAO 2008/12/12		MATERIAL NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				2 OF 3		

